What is claimed is:

1. A semiconductor package sawing apparatus comprising:

a pickup part having at least one pickup units for picking up an assembly of semiconductor packages;

a transfer part for transferring the pickup part in a predetermined direction;

a material supply part including at least one feeders for transferring a tray in a direction perpendicular to a transfer direction of the pickup part, to supply the assembly of semiconductor packages to the pickup part; and

a sawing part including at least one chuck tables for holding semiconductor packages supplied from the material supply part and at least one sawing units~~.~~,

wherein a seating part, on which a material accommodating groove is formed, provided between the material supply part and the chuck table of the sawing part, and the pickup part transfers the semiconductor material picked up from the material supply part to the chuck table by way of the seating part.

2. The semiconductor package sawing apparatus according to claim 1, wherein the material supply part includes a tray supply unit for stacking trays in which assemblies of semiconductor packages are accommodated and a tray discharge unit for stacking

empty trays, and the feeder includes a first feeder for transferring the tray from the tray supply unit to a pickup position of the pickup part and a second feeder for transferring the tray from which the assemblies of semiconductor packages are picked up by the pickup unit to the tray discharge unit.

3. The semiconductor package sawing apparatus according to claim 2, wherein the material supply part includes first guide rails and second guide rails arranged in a direction perpendicular to the transfer direction of the pickup part to support the tray so that the tray may be supplied from the tray supply unit or discharged to the tray discharge unit by the first or second feeder.

4. The semiconductor package sawing apparatus according to claim 3, wherein the material supply part further includes a tray pickup unit for picking up a tray from the first guide rails and seating the tray on the second guide rails.

~~5. The semiconductor package sawing apparatus according to claim 1, wherein a seating part, on which a material accommodating groove is formed, provided between the material supply part and the chuck table of the sawing part, and the pickup part transfers the semiconductor material picked up from~~

~~the material supply part to the chuck table by way of the seating part.~~

~~5~~6. The semiconductor package sawing apparatus according to claim ~~5~~1, wherein the seating part includes a driving means for driving the seating part in a direction perpendicular to the transfer direction of the pickup part transferred by the transfer part.

~~7~~6. The device according to claim ~~5~~1, wherein the number of material holding grooves formed on the chuck table to rest the assemblies of semiconductor packages and the number of the material accommodating grooves of the seating part are respectively a divisor of the number of material accommodating grooves of the tray.

~~8~~7. The semiconductor package sawing apparatus according to claim 1, wherein the pickup part has a single-pickup unit for picking up an individual assembly of semiconductor packages and a multi-pickup unit for simultaneously picking up a plurality of assemblies of semiconductor packages.

~~9~~8. The semiconductor package sawing apparatus according to claim ~~8~~7, wherein the pickup part includes a vision unit for acquiring position information of the semiconductor material by

photographing the semiconductor material accommodated in the accommodating groove of the tray or the semiconductor material accommodated in the accommodating groove of the seating part.

~~10. The semiconductor package sawing apparatus according to claim 1, wherein a cassette magazine for stacking and supplying semiconductor packages is detachably attached to one side of the material supply part in a modular form.~~

~~11~~9. ~~The semiconductor package sawing apparatus according to claim 10,~~

A semiconductor package sawing apparatus comprising:

a pickup part having at least one pickup units for picking up an assembly of semiconductor packages;

a transfer part for transferring the pickup part in a predetermined direction;

a material supply part including at least one feeders for transferring a tray in a direction perpendicular to a transfer direction of the pickup part, to supply the assembly of semiconductor packages to the pickup part; and

a sawing part including at least one chuck tables for holding semiconductor packages supplied from the material supply part and at least one sawing units and,

wherein a cassette magazine for stacking and supplying semiconductor packages is detachably attached to one side of the material supply part in a modular form,

wherein either of the first and second feeders of the material supply part is engaged with a conversion unit through an engaging member, the conversion unit being mounted to guide an assembly of semiconductor packages supplied in a direction parallel to the transfer direction of the pickup part from the cassette magazine which stacks and supplies the assemblies of semiconductor packages.

~~12~~10. The semiconductor package sawing apparatus according to claim ~~11~~9, wherein connection holes are provided in the feeder and the conversion unit respectively, and the engaging member is engaged with the connection holes of the feeder and the conversion unit.

~~13~~11. The semiconductor package sawing apparatus according to claim ~~11~~9, wherein the conversion unit includes a pair of guide rails, a supporting plate for mounting the guide rails, and a driving means for adjusting a width of the guide rails.

~~14~~12. The semiconductor package sawing apparatus according to claim ~~13~~11, wherein an individual driving means is provided at each of the guide rails so that the guide rails may be driven independently from each other so as to adjust the width between the guide rails and a position of each guide rail.

~~15~~13. The semiconductor package sawing apparatus according to claim ~~13~~11, wherein the driving means approaches or separates the guide rails by displacing the guide rails with a same distance, and the positions of the guide rails can be changed by moving the feeder engaged with the conversion unit.

~~16~~14. The semiconductor package sawing apparatus according to claim 11, wherein the pickup part further includes a gripper for gripping a front end of an assembly of semiconductor packages in the cassette magazine and withdrawing the assembly of semiconductor packages to the guide rails.

~~17~~15. The semiconductor package sawing apparatus according to claim 11, wherein a vision unit for acquiring position information of the assembly of semiconductor packages on the pickup unit or the guide rails is provided below a transfer path of the assembly of semiconductor packages transferred from

the material supply part to the chuck table of the sawing part through the pickup part or the guide rails.